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PUBLICLY AVAILABLE SPECIFICATION

PRE-STANDARD

Qualification and performance specification of permanent solder mask and flexible cover materials (standards.iteh.ai)





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IEC Central Office	Tel.: +41 22 919 02 11
3, rue de Varembé	Fax: +41 22 919 03 00
CH-1211 Geneva 20	info@iec.ch
Switzerland	www.iec.ch

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QUALIFICATION AND PERFORMANCE SPECIFICATION OF PERMANENT SOLDER MASK AND FLEXIBLE COVER MATERIALS

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Contact:

IPC 3000 Lakeside Drive, Suite 309S Bannockburn, Illinois 60015-1249 Tel 847 615.7100 Fax 847 615.7105

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Flexible Circuits Committee	Solder Mask Performance Task Group	Covercoat Materials Task Group
Chair Douglas O. Pauls Rockwell Collins	Chair David A. Vaughan Taiyo America, Inc.	Chair Steve A. Musante Raytheon Missile Systems
Vice-Chair Debora L. Obitz Trace Laboratories - East	Vice-Chair Douglas O. Pauls Rockwell Collins	
Technical Liaisons of the IPC Board of Directors		
Peter Bigelow IMI Inc.		
Sammy Yi Aptina Imaging Corporation		
Solder Mask Performance Task Group	nd Covercoat Materials Task Group	W
Gregory Bartlett, Teledyne Printed Circuit Technologies	Russell Griffith, Flexible Circuits Inc. Michael J. Jawitz, Boeing Satellite	Roger J. Miedico, Raytheon Company William Ortloff, Raytheon Company
John Bauer, Rockwell Collins	Development Center IEC PAS 61249-8-5:2014	Robert Sheldon, Pioneer Circuits Inc.
Michael Beauchesne, Amphenol Printed Circuits, Inc.	ten inck Koop, Minco Products Inc. Karin LaBerge, Microtek d aboratories	Terry Shepler, Electro-Materials, Inc.
Joshua Civiello, Defense Supply Center Columbus	John Leschisin, Minco Products Inc. Anne Lomonte, Draeger Medical	Corporation Brent Sweitzer, Multek Flexible
Mark Finstad, Flexible Circuit Technologies Inc	Systems, Inc.	Circuits, Inc. Steve I Vetter NSWC Crane
Thomas F. Gardeski, Gemini Sciences	Consulting	Clark F. Webster, ALL Flex LLC
Marc Goudreau, Vulcan Flex Circuit Corporation	Thomas McCarthy, Taconic Advanced Dielectric Division	Miou Yamaoka, Meiko Electronics Co. Ltd.

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